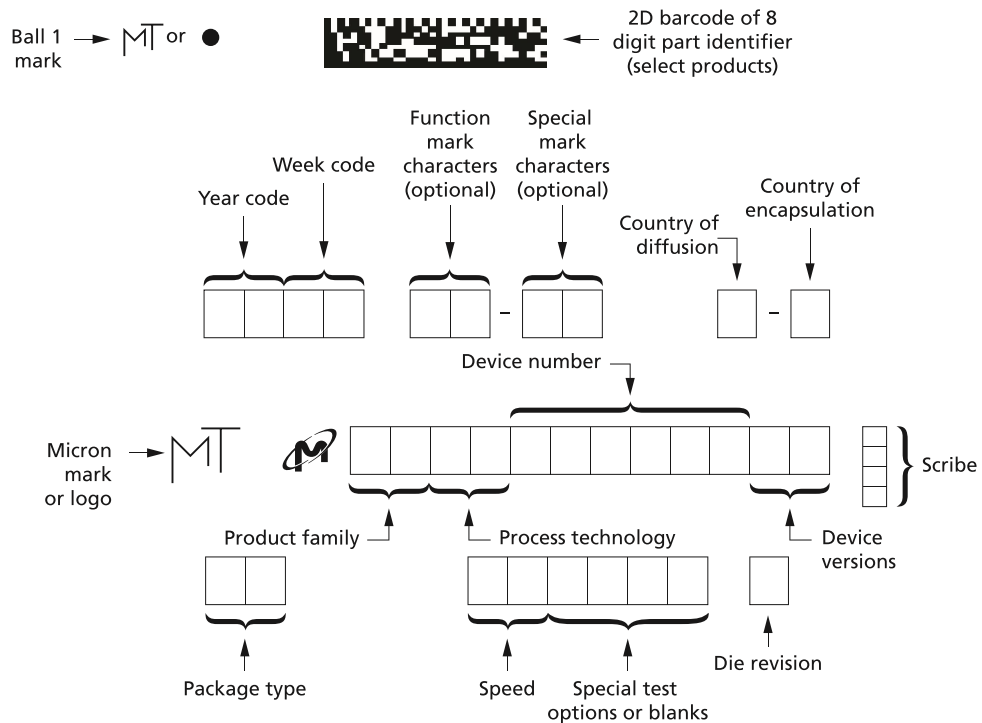


**Figure 1: TSOP Component Mark**



### Abbreviated Component Mark Information

Due to space limitations, FBGA-package component marks contain abbreviated details for two distinct types of information (see Figure 2 on page 6). The top row of the component mark contains the flooring details that are unrelated to product type:

- Date code (see below)
- Die revision
- Country of diffusion (see below for country codes)
- Country of encapsulation (see below for country codes)

Date codes are alphanumeric characters that indicate the year and workweek the parts were marked, in even-numbered workweeks. The first character is the last number in the year, and the second (alpha) character is the workweek.

A = 2	E = 10	I = 18	M = 26	Q = 34	U = 42	Y = 50
B = 4	F = 12	J = 20	N = 28	R = 36	V = 44	Z = 52
C = 6	G = 14	K = 22	O = 30	S = 38	W = 46	
D = 8	H = 16	L = 24	P = 32	T = 40	X = 48	

Codes for the countries of diffusion and encapsulation:

1 = USA	5 = China	B = Israel
2 = Singapore	7 = Taiwan	C = Ireland
3 = Italy	8 = Korea	D = Malaysia
4 = Japan	9 = Mixed	F = Philippines

The middle and bottom rows of the component mark contain product-specific details such as:

- Micron logo/ball 1 designator
- Coded part number